

pSEMI MATERIAL DECLARATION FORM

Product:	PE43614A-X
Ordering Codes:	PE43614A-X
Description:	Packaged 40GHz DSA
Package:	24L 4x4 LGA
Environmental Compliance	EU RoHS Directive 2011/65/EC and amendment 2015/863, REACH - EU ECHA SVHC, Arsenic Free, JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
Lead Finish	n/a
Availability	7/13/2020

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Silicon	7440-21-3	5.536520	13.72%	137,163.43
Die	Phosphorus	7723-14-0	0.000028	0.00%	0.69
Die	Boron	7440-42-8	0.000028	0.00%	0.69
Die	Arsenic	7440-38-2	0.000028	0.00%	0.69
Die	Germanium	7440-56-4	0.000028	0.00%	0.69
Die	Indium	7440-74-6	0.000028	0.00%	0.69
Die	Cobalt	7440-48-4	0.000028	0.00%	0.69
Die	Tungsten	7440-33-7	0.001042	0.00%	25.81
Die	Copper	7440-50-8	0.031595	0.08%	782.75
Die	Tantalum	7440-25-7	0.001499	0.00%	37.13
Die	Aluminum	7429-90-5	0.000579	0.00%	14.35
Substrate	Thermosetting resin (including filler)	Trade secret	2.419270	5.99%	59,935.73
Substrate	Glass cloth	65997-17-3	1.036830	2.57%	25,686.74
Substrate	Copper	7440-50-8	6.150993	15.24%	152,386.58
Substrate	Nickel	7440-02-0	0.204424	0.51%	5,064.45
Substrate	Zinc	7440-66-6	0.000230	0.00%	5.70
Substrate	Chromium	7440-47-3	0.000063	0.00%	1.55
Substrate	Silver	7440-22-4	0.000370	0.00%	9.16
Substrate	Impurity	Trade secret	0.001022	0.00%	25.31
Substrate	Acrylate/ epoxy resin reaction cured product	Trade secret	0.437817	1.08%	10,846.60
Substrate	Copper phthalocyanine blue	147-14-8	0.002065	0.01%	51.17
Substrate	Barium sulfate	7727-43-7	0.237166	0.59%	5,875.61
Substrate	Silica	7631-86-9	0.002896	0.01%	71.75
Substrate	Talc	14807-96-6	0.027359	0.07%	677.81
Substrate	Aromatic carbonyl compounds	Trade secret	0.025820	0.06%	639.67
Substrate	Dicyandiamide	461-58-5	0.000762	0.00%	18.88
Substrate	Amine compound	Trade secret	0.003368	0.01%	83.45
Substrate	Antifoam, Leveling agent, Additive	Trade secret	0.010365	0.03%	256.77
Substrate	Dibutyltin compound	683-18-1	0.000002	0.00%	0.06
Substrate	2-benzyl-2-dimethylamino-4'-morpholinobutyrophenone	119313-12-1	0.014480	0.04%	358.73
Substrate	Phosphorous	Trade secret	0.018579	0.05%	460.28
Substrate	Lead	7439-92-1	0.000114	0.00%	2.82
Substrate	Impurity	Trade secret	0.000223	0.00%	5.51
Substrate	Palladium	5/3/7440	0.004995	0.01%	123.75
Substrate	Impurity	Trade secret	0.000005	0.00%	0.12
Substrate	Gold	7440-57-5	0.004795	0.01%	118.80

Substrate	Impurity	Trade secret	0.000005	0.00%	0.12
Substrate	Tin	7440-31-5	0.011381	0.03%	281.96
Substrate	Antimony	7440-36-0	0.000004	0.00%	0.09
Molding Compound	Solid Epoxy Resin	Trade secret	2.417760	5.99%	59,898.32
Molding Compound	Phenol Resin	Trade secret	1.692432	4.19%	41,928.83
Molding Compound	Carbon Black	1333-86-4	0.241776	0.60%	5,989.83
Molding Compound	Metal Hydroxide	Trade secret	0.725328	1.80%	17,969.50
Molding Compound	Amorphous silica	60676-86-0	18.374976	45.52%	455,227.25
Molding Compound	Crystalline silica	14808-60-7	0.725328	1.80%	17,969.50
Total Weight (mg)			40.364403	100.00%	1,000,000